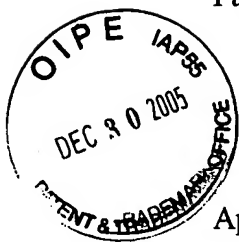


Applicant: T. S. Wong  
Application No.: 10/618,985  
Filed: July 14, 2003  
Page 1 of 14

Docket No. J003US



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: T. S. Wong  
Application No.: 10/618,985      Group Art Unit: 1732  
Filed: July 14, 2003      Examiner: Stefan Staicovici  
Title: THERMOPLASTIC MOLDING PROCESS

DEPOSITED: December <sup>22</sup>, 2005

~~REFERENCE~~  
I hereby certify that this correspondence is being deposited with the United States Postal Service ~~Express~~ Mail under 37 C.F.R. § 1.10 on the date indicated above and is addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria VA 22313-1450, MS Patent Application.

MS Patent Application.  
Commissioner for Patents  
P.O. Box 1450  
Alexandria VA 22313-1450

RESPONSE

Sir:

The October 4, 2005 Office Action ("Office Action") issued in connection with the above identified patent application finally rejected all of the pending claims. A Request for Continued Examination (RCE) of the application accompanies this Response. Please amend the RCE application as follows.